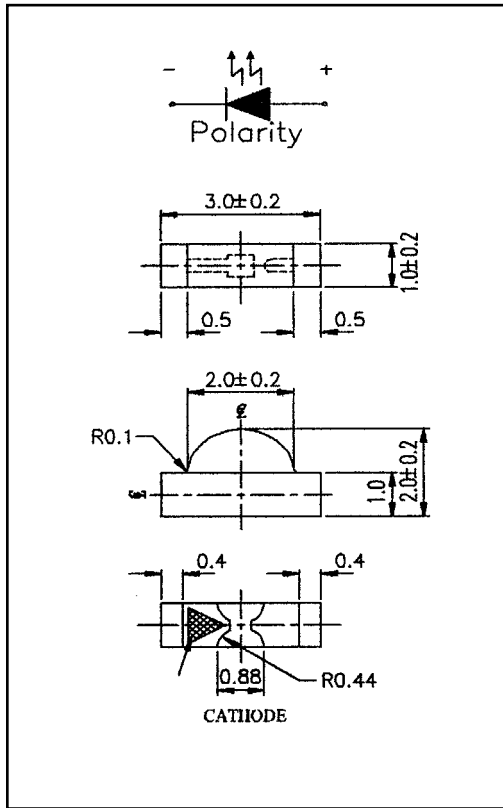




Unit: mm



AND4RRA

InGaAlP High Brightness Red Chip LED with Right Angle Lens on Surface Mount Package

Features

- 3.0 x 1.0 x 2.0 mm right angle SMD package
- All plastic mold type, clear colorless lens
- Peak wavelength ($\lambda_p=632\text{nm}$) high bright emission
- Low drive current: 1 to 20 mA
- Compatible with automatic placement equipment
- Compatible with infrared & vapor phase reflow solder process
- High efficiency
- RoHS Compliant

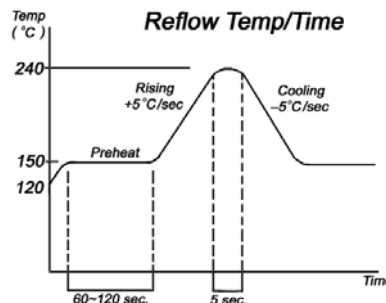
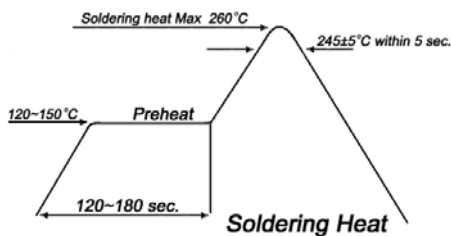
Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Forward Current	I_F	25	mA
Pulse Voltage Current (Duty Cycle: 1/10 @ 1KHz)	I_{FP}	100	mA
Operating Temperature	T_{Opr}	-40 ~ +85	$^\circ\text{C}$
Storage Temperature	T_{Stg}	-40 ~ +90	$^\circ\text{C}$
Electrostatic Discharge	ESD	2000	V
Soldering Temperature	T_{Sol}	260 ± 5 (<5 seconds)	$^\circ\text{C}$
Power Dissipation	P_d	60	mW
Reverse Voltage	V_R	5	V

Electro-Optical Characteristics ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V_F	$I_F = 20 \text{ mA}$	-	2.0	2.4	V
Reverse Current	I_R	$V_R = 5 \text{ V}$	-	-	10	μA
Luminous Intensity	I_V	$I_F = 20 \text{ mA}$	90	139	-	mcd
Peak Emission Wavelength	λ_p	$I_F = 20 \text{ mA}$	-	632	-	nm
Spectral Line Half Width	λ_d	$I_F = 20 \text{ mA}$	-	624	-	nm
Dominant Wavelength	$\lambda/2$	$I_F = 20 \text{ mA}$	-	20	-	nm
Full Viewing Angle	θ	$IV = 1/2 \text{ peak}$	-	120	-	degree

1. Recommended solder condition:



Product specifications contained herein may be changed without prior notice. It is therefore advisable to contact Purdy Electronics before proceeding with the design of equipment incorporating this product.

